

8-Oct		9-Oct		10-Oct		Date		
Venue	Hotel Metropolitan Sendai		Miyagino Ward Cultural Center in Sendai		Miyagino Ward Cultural Center in Sendai		Venue	
Room	Sendai-West	Sendai-East	Concert Hall	Theater Hall		Concert Hall	Theater Hall	Room
9:00			Registration (8:45-)	Preparation		Registration (8:45-)	Preparation	9:00
			B1L-B Plenary Talk II (9:00-9:40)			C1L-B Special Session: IEEE ELECTRONICS PACKAGING AWARD 2020 Recipients Talk (9:20-10:20)		
10:00			B2L-B Plenary Talk III (9:40-10:20)			Break (10:20-10:35)		10:00
			Break (10:20-10:35)					
11:00			B3L-B Session 3 : Integration Technology II (10:35-12:05)	Poster & Exhibition (10:20-18:30)		C2L-B Session 6 : 3D Design (10:35-12:05)		11:00
12:00								12:00
13:00	Registration (12:00-)		Lunch (12:05-13:30)			Lunch /TPC meeting (12:05-13:30)	Poster & Exhibition (9:00-16:00)	13:00
	Opening Remark (13:20-13:30)							
14:00	A1L-A Plenary Talk I (13:30-14:10)			B4P-C Poster Session (Core time: 13:30-15:00)	Exhibition	C3L-B Session 7 : Direct/Hybrid Bonding (13:30-15:00)		14:00
	A2L-A Session 1 : 3D Stacked Imager (14:10-16:05)							
	Break (14:40-14:55)							
15:00	(continued) A2L-A Session 1 : 3D Stacked Imager (14:10-16:05)		B5L-B Session 4 : Memory System (15:00-16:40)			Break (15:00-15:15)		15:00
	Break (16:05-16:20)					C4L-B Session 8: Thermal Management (15:15-16:25)		16:00
17:00	A3L-A Session 2 : Integration Technology I (16:20-17:50)		Break (16:40-16:55)	Poster & Exhibition (10:20-18:30)		Student Award Ceremony & Closing		17:00
			B6L-B Session 5 : Monolithic/Hetero Integration (16:55-18:05)					
18:00			Break (18:05-18:20)					18:00
19:00		Banquet (18:00-20:00)	B7L-B Panel Session (18:20-19:20)					19:00
20:00								20:00
21:00								21:00